

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) An input signal processing device, comprising:
an input signal terminal that receives an input signal;
a connection inductance element ~~that is~~ connected to said input signal terminal at one end thereof;
a connection capacitance element ~~that is~~ connected to said input signal terminal at one end thereof;
a first grounding switching means that ~~switches whether the~~ selectively grounds ~~an~~ other end of said connection inductance element ~~is grounded or not~~; and
a second grounding switching means that ~~switches whether the~~ selectively grounds an other end of said connection capacitance element ~~is grounded or not~~.
2. (Original) The input signal processing device according to claim 1, further comprising:
a grounding capacitance element that is connected to the other end of said connection inductance element, and is grounded; and
a grounding inductance element that is connected to the other end of said connection capacitance element, and is grounded.

3. (Previously Presented) The input signal processing device according to claim 1, wherein at least one of said first grounding switching means and said second grounding switching means is a semiconductor switch or an MEMS switch.

4. (Previously Presented) A high-frequency component acquisition method that uses the input signal processing device according to claim 1 to acquire a high-frequency component from the input signal, comprising:

a first intermediate portion grounding step of using said first grounding switching means to ground the other end of said connection inductance element; and

a second intermediate portion signal acquiring step of acquiring a signal output from the other end of said connection capacitance element.

5. (Previously Presented) A low-frequency component acquisition method that uses the input signal processing device according to claim 1 to acquire a low-frequency component from said input signal, comprising:

a second intermediate portion grounding step of using said second grounding switching means to ground the other end of said connection capacitance element; and

a first intermediate portion signal acquiring step of acquiring a signal output from the other end of said connection inductance element.

6. (Previously Presented) The input signal processing device according to claim 2, wherein at least one of said first grounding switching means and said second grounding switching means is a semiconductor switch or an MEMS switch.

7. (Previously Presented) A high-frequency component acquisition method that uses the input signal processing device according to claim 2 to acquire a high-frequency component from the input signal, comprising:

a first intermediate portion grounding step of using said first grounding switching means to ground the other end of said connection inductance element; and

a second intermediate portion signal acquiring step of acquiring a signal output from the other end of said connection capacitance element.

8. (Previously Presented) A high-frequency component acquisition method that uses the input signal processing device according to claim 3 to acquire a high-frequency component from the input signal, comprising:

a first intermediate portion grounding step of using said first grounding switching means to ground the other end of said connection inductance element; and

a second intermediate portion signal acquiring step of acquiring a signal output from the other end of said connection capacitance element.

9. (Previously Presented) A high-frequency component acquisition method that uses the input signal processing device according to claim 6 to acquire a high-frequency component from the input signal, comprising:

a first intermediate portion grounding step of using said first grounding switching means to ground the other end of said connection inductance element; and

a second intermediate portion signal acquiring step of acquiring a signal output from the other end of said connection capacitance element.

10. (Previously Presented) A low-frequency component acquisition method that uses the input signal processing device according to claim 2 to acquire a low-frequency component from said input signal, comprising:

a second intermediate portion grounding step of using said second grounding switching means to ground the other end of said connection capacitance element; and

a first intermediate portion signal acquiring step of acquiring a signal output from the other end of said connection inductance element.

11. (Previously Presented) A low-frequency component acquisition method that uses the input signal processing device according to claim 3 to acquire a low-frequency component from said input signal, comprising:

a second intermediate portion grounding step of using said second grounding switching means to ground the other end of said connection capacitance element; and

a first intermediate portion signal acquiring step of acquiring a signal output from the other end of said connection inductance element.

12. (Previously Presented) A low-frequency component acquisition method that uses the input signal processing device according to claim 6 to acquire a low-frequency component from said input signal, comprising:

a second intermediate portion grounding step of using said second grounding switching means to ground the other end of said connection capacitance element; and

a first intermediate portion signal acquiring step of acquiring a signal output from the other end of said connection inductance element.

13. (New) An input signal processing device, comprising:

- an input signal terminal that receives an input signal;
- a connection inductance element connected to said input signal terminal at one end thereof;
- a connection capacitance element connected to said input signal terminal at one end thereof;
- a first grounding switch that selectively grounds an other end of said connection inductance element and
- a second grounding switch that selectively grounds an other end of said connection capacitance element.

14. (New) The input signal processing device according to claim 13, further comprising:

- a grounding capacitance element connected to the other end of said connection inductance element, and is grounded; and
- a grounding inductance element connected to the other end of said connection capacitance element, and is grounded.

15. (New) The input signal processing device according to claim 13, wherein at least one of said first grounding switch and said second grounding switch comprises one of a semiconductor switch and a MEMS switch.

16. (New) A high-frequency component acquisition method that uses the input signal processing device according to claim 13 to acquire a high-frequency component from the input signal, comprising:

using said first grounding switch to selectively ground an other end of the connection inductance element; and

acquiring a signal output from the other end of the connection capacitance element.

17. (New) A low-frequency component acquisition method that uses the input signal processing device according to claim 13 to acquire a low-frequency component from said input signal, comprising:

using said second grounding switch to selectively ground an other end of the connection capacitance element; and

acquiring a signal output from the other end of the connection inductance element.